

3.0A SURFACE MOUNT SUPER-FAST RECTIFIER

Features

- Glass Passivated Die Construction
- Super-Fast Recovery Time For High Efficiency
- Surge Overload Rating to 100A Peak
- Ideally Suited for Automated Assembly
- Lead Free Finish/RoHS Compliant (Note 1)
- **Green Molding Compound (No Halogen and Antimony)**

Mechanical Data

- Case: SMB/SMC
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Lead Free Plating (Matte Tin Finish). Solderable per MIL-STD-202, Method 208 (e3)
- Polarity: Cathode Band or Cathode Notch
- SMB Weight: 0.093 grams (approximate)
- SMC Weight: 0.21 grams (approximate)





Bottom View

Ordering Information (Note 3)

Part Number	Case	Packaging
ES3x-13-F	SMC	3000/Tape & Reel
ES3xB-13-F	SMB	3000/Tape & Reel

^{*} x = Device type, e.g. ES3A-13-F (SMC package); ES3AB-13-F (SMB package).

Notes:

- 1. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied, see EU Directive 2002/95/EC Annex Notes.
- 2. Product manufactured with Data Code 0924 (week 24, 2009) and newer are built with Green Molding Compound.
- 3. For packaging details, go to our website at http://www.diodes.com.

Marking Information



ES3x = Product type marking code, ex: ES3A (SMC package) ES3xB = Product type marking code, ex: ES3AB (SMB package) □ = Manufacturers' code marking YWW = Date code marking Y = Last digit of year (ex: 2 for 2002) WW = Week code (01 to 53)



Maximum Ratings @TA = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitance load, derate current by 20%.

Characteristic	Symbol	ES3A/AB	ES3B/BB	ES3C/CB	ES3D/DB	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage (Note 4)	$egin{array}{c} V_{RRM} \ V_{R} \end{array}$	50	100	150	200	\ \
RMS Reverse Voltage	V _{R(RMS)}	35	70	105	140	V
Average Rectified Output Current @ T _T = 100°C	Ю		3.	.0		Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}		10	00		А

Thermal Characteristics

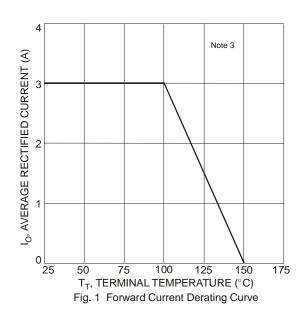
Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Terminal	$R_{ heta JT}$	10	°C/W
Typical Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	50	°C
Operating and Storage Temperature Range	T _{J,} T _{STG}	-55 to +150	°C

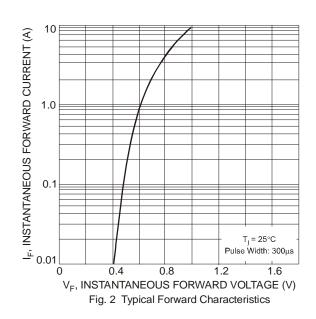
Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic		Symbol	Value	Unit
Maximum Forward Voltage	@ $I_F = 3.0A$	V_{FM}	0.9	V
Peak Reverse Current at Rated DC Blocking Voltage (Note 4)	@ T _A = 25°C @ T _A = 125°C	I _{RM}	10 500	μА
Maximum Reverse Recovery Time (Note 6)		t _{rr}	25	ns
Typical Total Capacitance (Note 7)		C _T	45	pF

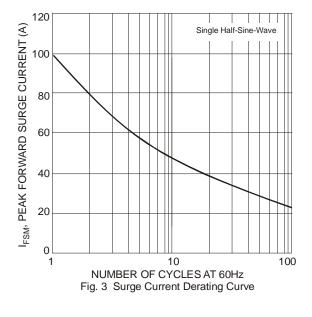
Notes:

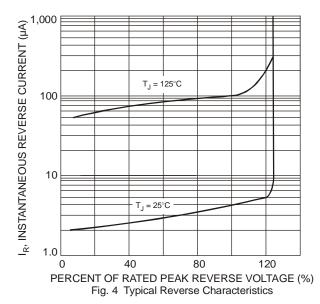
- 4. Short duration pulse test used to minimize self-heating effect.
- 5. Unit mounted on PC board with 5.0 mm² (0.013 mm thick) copper pads as heat sink. 6. Measured with $I_F = 0.5A$, $I_R = 1.0A$, $I_{rr} = 0.25A$. See Figure 5. 7. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

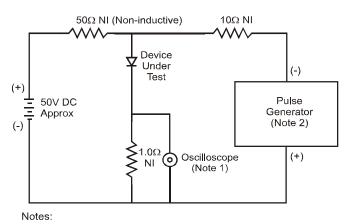


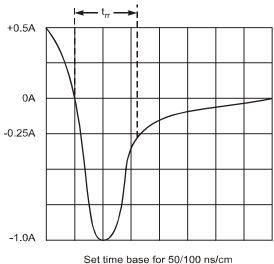








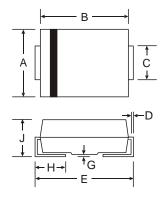




- 1. Rise Time = 7.0ns max. Input Impedance = 1.0M Ω , 22pF.
- 2. Rise Time = 10ns max. Input Impedance = 50Ω .

Fig. 5 Reverse Recovery Time Characteristic and Test Circuit

Package Outline Dimensions

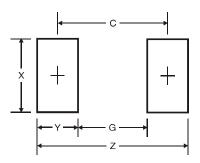


SMB				
Dim	Min	Max		
Α	3.30	3.94		
В	4.06	4.57		
С	1.96	2.21		
D	0.15	0.31		
Е	5.00	5.59		
G	0.05	0.20		
Н	0.76	1.52		
J	2.00	2.50		
All Dimensions in mm				

SMC				
Dim	Min	Max		
Α	5.59	6.22		
В	6.60	7.11		
С	2.75	3.18		
D	0.15	0.31		
Е	E 7.75 8.13			
G 0.10 0.20				
H 0.76 1.52				
J	2.00	2.50		
All Dimensions in mm				



Suggested Pad Layout



SMB Dimensions	Value (in mm)	
Z	6.7	
G	1.8	
X	2.3	
Y	2.5	
С	4.3	

SMC Dimensions	Value (in mm)	
Z	9.3	
G	4.4	
Х	3.3	
Y	2.5	
С	6.8	

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